

IN THE SPECIFICATION

It is requested that Paragraph 13 of the specification should be replaced with the following substitute paragraph:

[0013] The above-mentioned need is met by the present invention, which provides a laminated component including a separator having first and second surfaces, a conductive film layer disposed against the first surface of the separator, and a non-conductive film layer disposed against the second surface of the separator. The conductive and non-conductive film layers both have larger lateral dimensions than the separator such that a portion of each film layer extends beyond the separator. The extending portions of the conductive and non-conductive film layers are joined together to seal the laminated component. In one embodiment, a band of adhesive is disposed on a first surface of the conductive film layer so as to define an enclosed central area inwardly thereof and the separator is placed within the central area. The extending portion of the non-conductive film layer is pressed against the adhesive to form a joint between the conductive film layer and the non-conductive film layer. The term non-conductive layer as used herein is defined as a film layer that is discardable and will not form a functional conductive element of a printed circuit board without regard to the conductivity of the film layer.

It is requested that Paragraph 23 of the specification should be replaced with the following substitute paragraph:

[0023] The non-conductive film layer 16 is placed over the separator 14 so that a first or inner surface 26 of the non-conductive layer 16 is disposed flat against a second surface 28 of the separator 14. The non-conductive film layer 16 is discardable after the processing described below in relation to Figure 4, and will not form a functional conductive element of a printed circuit board manufactured according to the present invention. The film layer 16 may be formed from conductive materials but will not form a functional conductive element in the final product of the invention. The lateral dimensions of the non-conductive film layer 16 are larger than that of the separator 14 so that the non-conductive film layer 16 extends beyond the separator 14 on all sides thereof. Specifically, the non-conductive film layer dimensions at least match the dimensions of the strips of adhesive 18 and can be equivalent to the lateral dimensions

of the conductive film layer 12 as is shown in the Figures. The non-conductive film layer 16 is a thin sheet of a ~~non-conductive~~ material such as aluminum, polytetrafluoroethylene (PTFE), or silicone. The non-conductive film layer 16 can be any thickness, but a thickness in the range of about 17.8-127 microns is typical.